

DECEMBER 7, 2022 (Wednesday)						
08:00am - 09:00am	Registration					
GPW Hotel, Room	Riverfront I	Riverfront II	Riverfront III	Waterfront I	Waterfront II	Waterfront III
	PDC: Reliability Engineering Testing Methodology and Statistical Knowledge for Qualifications of Consumer and Automotive Electronic Components Dr Fen Chen, Cruise LLC (a GM company)	PDC: Photonic Technologies for Communication, Sensing, and Displays Dr Torsten Wipiejewski, Huawei Technologies	PDC: Reliability of Heterogeneous Integration (HI) Systems - Reliability Needs of HI Stakeholders Prof SB Park, The State University of New York	PDC: Fan-Out Packaging and Chiplet Heterogeneous Integration Dr John H Lau, Unimicron Technology		PDC: Advanced Packaging for MEMS and Sensors Dr Horst Theuss, Infineon Technologies
10:15am - 10:35am	Coffee/Tea Break					
10:35am - 12:00pm	PDC (con't)	PDC (con't)	PDC (con't)	PDC (con't)		PDC (con't)
12:00pm - 01:00pm	Lunch					
	Waterfront Ball Room					
01:00pm - 1:30pm	Grand Opening Ceremony					
	Welcome address, Dr Chandra Rao Bhesetti, General Chair EPTC 2022					
	Opening Speech, Dr Kitty Pearsall, IEEE EPS President					
	Keynote : Challenges and Opportunities in Heterogeneous Integration					
1:30pm - 02:15pm	Dr Ravi Mahajan, Intel Fellow, Intel					
	Keynote : New Directions and Challenges in the Packaging of AR/VR Hardware					
02:15pm - 03:00pm	Dr Raj Pendse, Director of Si Packaging, Meta Reality Lab					
03:00pm - 03:15pm	Coffee/Tea Break (Waterfront Foyer)					
	Keynote : Materials Engineering Innovations to address Next-Gen Electronics Packaging Challenges					
03:15pm - 04:00pm	Dr Sundar Ramamurthy, VP & GM Advanced Packaging, Applied Materials					
	EPTC Panel Session : Chiplet as An Enabler for System Scaling					
04:00pm - 05:30pm	Ravi Mahajan (Intel), Dielacher Bernd (EVG), Raj Pendse (Meta), Yik Yee Tan (Yole Intelligence)					
06:30pm - 08:30pm	VIP Dinner (by invitation only)					
DECEMBER 8, 2022 (Thursday)						
	Veranda I	Veranda II	Veranda III	Riverfront I	Riverfront II	Riverfront III
08:30am - 9:50am	A1: 2.5D, 3D and WL Packaging	A2: Hybrid Bonding Processes and Materials 1	A3: Wafer Level Processing I	A4: Leadframe and Substrate Manufacturing I	A5: Electrical Simulations & Characterizations I	A6: Soldered and Sintered Interconnections I
9:50am - 10:20am	Coffee/Tea Break (Waterfront Foyer)					
	Veranda I	Veranda II	Veranda III	Riverfront I	Riverfront II	Riverfront III
10:20am - 11:40pm	B1: Thermo-mechanical Modeling & Simulation I	B2: Hybrid Bonding Processes and Materials 2	B3: Wafer Level Processing II	B4: Leadframe and Substrate Manufacturing II	B5: Thermal Management & Characterization I	B6: Soldered and Sintered Interconnections II
11:40am - 1:10pm	EPS Luncheon					
	EPS Presentations: Student Travel Grants, EPTC OC Appreciation Ceremony					
		Veranda III			Riverfront II and III (Combined rooms)	
1:10pm - 2:25pm		Packaging Education Workshop. Chairs: Jeff Suhling and Andrew Tay, Speakers: K.N. Chhang, Weihua Zhu, Ge-Sung Kim, Anandaroop Bhattacharya & Chuan Seng Tan			Exhibitor Presentations 1: Lam Research, ASE, ERS, PacTech, Indium, RBN	
	Interactive Presentations 1 at Waterfront Foyer (2:25pm to 3:55pm)					
	Veranda I	Veranda II	Veranda III	Riverfront I	Riverfront II and III (Combined rooms)	
2:25pm - 3:25pm	C1: Thermo-mechanical Modeling & Simulation II	C2: Advanced Optoelectronics and Displays	C3: Assembly Manufacturing and Tests	C4: Lithography and Laser Direct Imaging	C5: Thermal Management and Characterization II	
3:25pm - 3:55pm	Coffee/Tea Break (Waterfront Foyer)					
3:55pm - 5:15pm	D1: Fan-Out Packaging	D2: Assembly Materials and Processing I	D3: Quality, Reliability & Failure Analysis	D4: Semiconductor Manufacturing & Deep Learning	D5: Emerging Technologies	D6: Assembly and Manufacturing Technology I
5:30pm - 5:45pm	Transport to HarbourFront's Cable Car Station					
6:00pm - 9:30pm	EPTC Conference Banquet @ Mount Faber					
DECEMBER 9, 2022 (Friday)						
	Veranda I	Veranda II	Veranda III	Riverfront I	Riverfront II	Riverfront III
	Invited Presentations A	Invited Presentations B	Invited Presentations C	Invited Presentations D	Invited Presentations E	Invited Presentations F
08:30am - 09:00am	Understanding of Hybrid Bonding Mechanism by Utilizing Molecule Simulation Approach Dr Minwoo Rhee, Samsung	Path Finding to Maximization of AI/HPC/GPC System Performance Dr Gamal Refai-Ahmed, AMD	SAB for 3D and Heterogeneous Integration of Semiconductor Substrates & Devices Prof Tadatomu Suga, The University of Tokyo	Submicron Nanosecond Thermoreflectance Imaging for Thermal and Failure Analysis Dr Mo Shakouri, Microsanj	Advanced Fan-Out Packaging for Chiplet Integration, Yu-Po Wang, SPIL	Hybrid Bonding – State-of-the-Art and Upcoming Requirements in W2W and D2W Dr Bernd Dielacher, EV Group
09:00am - 10:00am	E1: Thermo-mechanical Modeling & Simulation III	E2: RF Modeling, Designs and Characterizations	E3: Wire Bonding and Reliability I	E4: Solder Interconnections Reliability	E5: Wafer Level Processing III	E6: Smart Manufacturing & Equipment Tech
10:00am - 10:30am	Coffee/Tea Break (Waterfront Foyer)					
10:30am - 11:50pm	F1: Assembly and Manufacturing Technology II	F2: Hybrid Bonding Processes and Materials 3	F3: Assembly Materials and Processing II	F4: MEMS and Wafer Level Processing	F5: Thermal Management & Characterization III	F6: Antenna Designs and AIP Processing
	Waterfront Ballroom					
11:50pm - 1:20pm	EPTC Luncheon					
	EPTC Highlights; EPTC 2021 Best Papers Announcement & Awards Giving; Sponsorship/ Exhibition Appreciation Ceremony					
GPW Hotel, Room			Veranda III	Riverfront I, II and III		
1:20pm - 2:35pm			Chapter Chairs' Meeting	Exhibitors Presentations 2: TORAY, Advantest, Heraeus, Lightspeed, Microsanj		
	Interactive Presentations 2 at Waterfront Foyer (2:35pm to 4:05pm)					
	Veranda I	Veranda II	Veranda III	Riverfront I, II and III		
2:35pm - 3:35pm	G1: Electrical Simulations & Characterizations II	G2: Flexible Substrate and Manufacturing	G3: Wire Bonding and Reliability II	Heterogeneous Integration Roadmap (HIR) Workshop Chair: Andrew Tay, NUS HIR Overview - Ravi Mahajan, Intel Supply Chain - Kitty Pearsall, IEEE EPS President		
3:35pm - 4:00pm	Coffee/Tea Break (Waterfront Foyer)					
4:00pm - 5:00pm				Thermal Management - Gamal Refai-Ahmed AMD 2D-3D & Interconnect - Ravi Mahajan, Intel Photonics - Amr Helmy, University of Toronto		
	Riverfront I, II and III					
5:00pm - 5:30pm	Closing Ceremony and Lucky Draw					